



## Physical Interface & Carriers Japan TC Chapter

Japan Standards Summer 2023 Meetings  
July 21  
SEMI Japan office, Tokyo, Japan/WEB  
13:30-16:30 (JST)

### SVM Software (for voting) ※SVM へのログインもお願いします。

1. Open a Web browser and go to: <https://svm.semi.org/> (Do not use Internet Explorer or MS Edge)
2. Click "Login"
3. Enter your Standards Membership username and password (same login for voting on ballots).
1. If you have forgotten your username and/or password, they may be retrieved at: <https://ams.semi.org/ebusiness/ForgotUID.aspx>
2. Find the meeting room: < **Physical Interfaces & Carriers Japan TC Chapter Meeting – July 21,2023**>
3. Click "Go"

## AGENDA

### 1.0 Welcome / Call to Order

- 1.1 Introductions
- 1.2 Meeting Reminders (*Membership Requirement, Antitrust and Intellectual Property Reminders, Effective Meeting Guidelines*)
- 1.3 Agenda Review

### 2.0 Review of Previous Meeting Minutes

### 3.0 Liaison Report

- 3.1 North America

### 4.0 Staff Report

### 5.0 Ballot Review

None

### 6.0 Subcommittee & Task Force Reports

- 6.1 Global PIC Standards Maintenance TF
- 6.2 Japan Electron Microscopy Workflow liaison TF
- 6.3 Panel Level Packaging Panel FOUP TF
- 6.4 [Liaison: 3D Packaging & Integration JA TC Chapter] Panel Level Packaging Glass Carrier TF
- 6.5 [Liaison: 3D Packaging & Integration NA TC Chapter] Panel Level Packaging Panel TF

### 7.0 Old Business

- 7.1 Project Period Review
- 7.2 5-Year Review

### 8.0 New Business

- 8.1 Proposal of New Activity
  - 8.1.1 SNARF Proposal for Line Item Revision to SEMI E181-0423 SPECIFICATION FOR PANEL FOUP FOR PANEL LEVEL PACKAGING, SEMI E181.1-0423 - SPECIFICATION FOR PANEL FOUP FOR 510 mm – 515 mm PANEL SIZE and 12 SLOTS, SEMI E181.2-0423 - SPECIFICATION FOR PANEL FOUP FOR 510 mm – 515 mm PANEL SIZE and 6 SLOTS, SEMI E181.3-0423 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 12 SLOTS, SEMI E181.4-0423 - SPECIFICATION FOR PANEL FOUP FOR 600 mm – 600 mm PANEL SIZE and 6 SLOTS
  - 8.1.2 SNARF Proposal for Line Item Revision to Line Item Revision to SEMI E182-0621 - SPECIFICATION FOR PANEL FOUP LOADPORT FOR PANEL LEVEL PACKAGING



**9.0 Action Item Review**

9.1 Open Action Items

9.2 New Action Items

**10.0 Next Meeting and Adjournment**